

### Bill of materials for using a Hall IC

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimension mm(inches)
1	IC1	1	-	TPD4152F	TOSHIBA		HSSOP31	17.5 x 11.93
2	R1	1	820 mΩ	SL1TTER85F	KOA	1 W, ±1%	-	6.3 x 3.2 (2512)
3	R2	1	27 kΩ			200 mW, ±1%	-	1.6 x 0.8 (0603)
4	R3	1	5.1 kΩ			200 mW, ±5%	-	1.6 x 0.8 (0603)
5	R4	1	100 Ω			200 mW, ±5%	-	1.6 x 0.8 (0603)
6	R5, R6, R7	3	5.1 kΩ			200 mW, ±5%	-	1.6 x 0.8 (0603)
7	R11, R12	2	4.7 kΩ			200 mW, ±1%	-	1.6 x 0.8 (0603)
8	C1, C2, C3	3	2.2 μF			Ceramic, 25 V, ±10%	-	2.0 x 1.2 (0805)
9	C4, C14	2	1 nF			Ceramic, 25 V, ±10%	-	1.6 x 0.8 (0603)
10	C5	1	10 μF			Ceramic, 25 V, ±20%	-	1.6 x 0.8 (0603)
11	C6, C15	2	100 nF			Ceramic, 25 V, ±10%	-	1.6 x 0.8 (0603)
12	C12, C13	2	1 μF	ECQE6105KF	Panasonic	Polypropylene Film, 630V, ±10 %	DIP	

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